

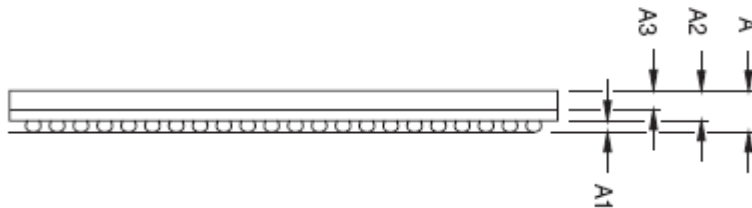
CUSTOMER ADVISORY ADV0607

UFBGA 484 Package Coplanarity Enhancement

Change Description

Altera will enhance the coplanarity of its Ultra FineLine BGA[®] (UFBGA) 484 packages as part of the company's continuous product-quality improvement process. This enhancement does not involve any material changes. The mold cap thickness, represented as A3 in figure 1 below, is typically 0.80 mm for presently shipping pre-change UFBGA 484 packages. The coplanarity-enhanced package will have a typical A3 value of 0.95 mm. The overall package height will remain within the maximum specified value of 2.20 mm, while the typical package thickness will increase by 0.15 mm. There is no change to the moisture sensitivity rating.

Figure 1. UFBGA 484 Package Dimensions



Reason for Change

This change is to further ensure manufacturing robustness in the increasing range of reflow conditions required in today's board manufacturing environments. This UFBGA 484 package coplanarity enhancement is the result of Altera's continuous product-quality improvement process.

Products Affected

Table 1 lists the product lines affected by this change.

Table 1. Products Affected by UFBGA 484 Coplanarity Enhancement

Package	Product Line
UFBGA 484	EP2C35
	EP2C50

Product Traceability and Transition Dates

This change will be implemented in January 2007. Customers may receive products with this change beginning with a date code marking of 0701 on top of the package (see Figure 2).

Figure 2. Date Code Marking Format

Altera Date Code Marking Format
A XβZαα 0701 T

Contact:

For more information on this advisory, please contact Altera® Customer Quality support at customer-quality@altera.com.

In accordance with JESD46-B, this change is deemed acceptable to the customer if no acknowledgement is received within 30 days from this notification.

Revision History:

Rev	Date Released	Description of Change
0	21-Nov-06	Initial Release